

Part Number: **BAT46W-7-F**
Weight (mg): 10.529

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Die,Schottky	Doped silicon	Doped silicon *	7440-21-3	100.00%	1.061	0.112	1000000	10611
SOD-123 leadframe	Alloy 42	Fe	7439-89-6	57.65%	28.448	2.995	576500	164001
		Ni	7440-02-0	41.00%			410000	116636
		Mn	7439-96-5	0.60%			6000	1707
		Cr(not Cr 6+)	7440-47-3	0.10%			1000	284
		Co	7440-48-4	0.50%			5000	1422
		Si	7440-21-3	0.15%			1500	427
	Pure silver	Ag	7440-22-4	100.00%	0.863	0.091	1000000	8632
Bonding wire	1.0mil	Au	7440-57-5	100.00%	0.132	0.014	1000000	1322
Molding compound	KTMC-1050G	SiO2	60676-86-0	69.00%	67.151	7.071	690000	463339
		Epoxy Resin	29690-82-2	14.00%			140000	94011
		Phenol Resin	9003-35-4	7.00%			70000	47005
		Mg(OH)2	1309-42-8	8.00%			80000	53720
		C	1333-86-4	0.20%			2000	1343
		others	----	1.80%			18000	12087
Die attached epoxy	9005SP	Ag	7440-22-4	80.00%	0.318	0.033	800000	2541
		Bisphenol F	28064-14-4	15.00%			150000	477
		Glycidyl neodeconate	26761-45-5	5.00%			50000	159
Tin solder	Pure Tin	Sn	7440-31-5	100.00%	2.027	0.213	1000000	20275
					100.00	10.529		1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, Material Composition Declaration for Electronic Products.

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

Antimony compounds	Organic tin compounds
Asbestos	Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Azo compounds	Ozone Depleting Substances - Class II (HCFCs)
Cadmium and cadmium compounds	Perfluorooctane Sulphonate (PFOS) or related compounds
Certain Shortchain Chlorinated Paraffins	Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Chlorinated organic compounds	Polychlorinated Biphenyls (PCBs)
Halogens	Polychlorinated Naphthalenes (> 3 chlorine atoms)
Hexavalent chromium compounds	Radioactive Substances
Lead and lead compounds	Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Mercury and mercury compounds	Tributyl Tin Oxide (TBTO)

This product or product family does not contain any chemicals designated by the European Chemicals Agency (ECHA) as Substances of Very High Concern (SVHCs) under REACH. Please check the document at http://www.diodes.com/files/products_lead_free/RoHS_Product_List.pdf for the current compliance status.